

REMARKS

Favorable reconsideration of this application, in light of the following discussion and in view of the present amendment, is respectfully requested.

Claim 16 is cancelled. Claims 11, 17, 21 and 24 are amended. Claims 11-15, 17-21, 23 and 24 are pending.

I. Rejection under 35 U.S.C. § 103

In the Office Action, at page 2, numbered paragraph 1, claims 11-21, 23 and 24 were rejected under 35 U.S.C. § 103(a) as being unpatentable over WO 2003/030247 to Hase et al. in view of U.S. Patent No. 6,365,498 to Chu et al. This rejection is respectfully traversed because the combination of the teachings of Hase and Chu does not suggest:

a single active semiconductor component arranged on the substrate and having an outer electrical contact surface, the single active semiconductor component being a power semiconductor component;...

wherein the electrical connection line is part of at least one discrete passive electrical component arranged on the substrate,

as recited in amended independent claims 11 and 24.

Hase discusses that an upper surface 20 of a substrate 1 is populated with semiconductor chips 2. A film 3 made of electrically insulating plastic is laminated under vacuum onto the surface 20 of the substrate 1 so that the film 3 covers with a tight fit the surface 20 containing the contact surfaces 210 and adheres to this surface 20. Planar contact is made with an exposed contact surface 210 and 112 by a layer 4 made of electrically conducting material.

As conceded by the Examiner, Hase does not discuss or suggest that the electrical connection line 4 is part of at least one discrete passive electrical component arranged on a substrate. The Examiner indicates that Chu makes up for the deficiencies in Hase. The Applicants respectfully disagree.

Chu discusses an IC device 20 which includes a substrate 22, a passivation layer 28, a bond pad 24, and a copper trace 40 in communication with the bond pad 24.

Chu does not discuss or suggest that the integrated circuit (IC) chip, including the bond pad 24, is a semiconductor component which is a power semiconductor component. Chu is

concerned only with an integrated circuit, but is not concerned with power semiconductor devices.

While the Examiner alleges that Hase and Chu would be combined “for the purpose of providing integrated circuit devices with both active and passive elements, while reducing manufacturing costs by integrating methods for I/O redistribution and passive components fabrication,” the cited motivation does not suggest combining the device of Hase with that of Chu, as Chu is directed not to a power semiconductor device, but is directed to an integrated circuit. The cited motivation gives no indication as to how or why the integrated circuit of Chu would be incorporated with the device of Hase, when Chu does not suggest the use of a circuit having a semiconductor component, which is a power semiconductor component.

Therefore, as the combination of the teachings of Hase and Chu does not discuss or suggest “a single active semiconductor component arranged on the substrate and having an outer electrical contact surface, the single active semiconductor component being a power semiconductor component,” as recited in amended independent claims 11 and 24, claims 11 and 24 patentably distinguish over the references relied upon. Accordingly, withdrawal of the §103(a) rejection is respectfully requested.

Further, the combination of the teachings of Hase and Chu does not discuss or suggest “producing a single active semiconductor component on a substrate, the single active semiconductor component having an outer electrical contact surface facing away from the substrate, the single active semiconductor component being a power semiconductor component; and producing an electrical connection line that contacts the outer electrical contact surface of the semiconductor component, the electrical connection line being part of a discrete passive electrical component,” as recited in amended independent claim 21. Therefore, claim 21 patentably distinguishes over the references relied upon. Accordingly, withdrawal of the §103(a) rejection is respectfully requested.

Claims 12-15, 17-20 and 23 depend either directly or indirectly from independent claims 11 and 21 and include all the features of their respective independent claims, plus additional features that are not discussed or suggested by the references relied upon. For example, claim 15 recites that “the discrete passive electrical component is a part of a sensor of a physical variable.” Therefore, claims 12-15, 17-20 and 23 patentably distinguish over the references relied upon. Accordingly, withdrawal of the §103(a) rejection is respectfully requested.

Conclusion

In accordance with the foregoing, claim 16 has been cancelled. Claims 11, 17, 21 and 24 has been amended. Claims 11-15, 17-21, 23 and 24 are pending and under consideration.

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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